

DESIGNED & DIMENSIONED
IN INCHES [MILLIMETERS]

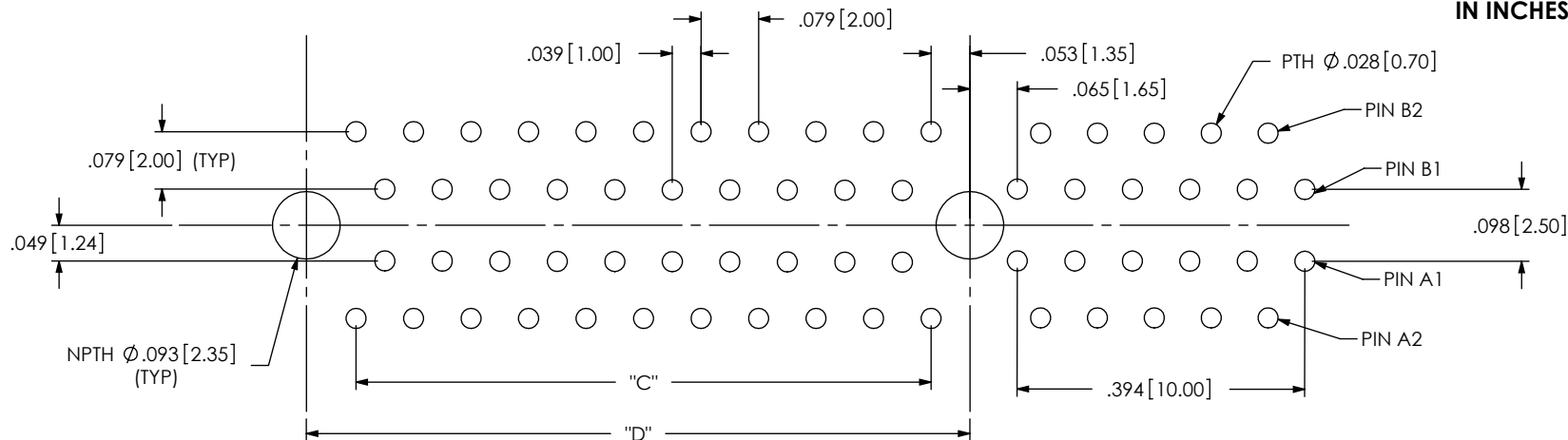


FIG 1
RECOMMENDED PCB LAYOUT
(FOR: -036, -064 & -164)

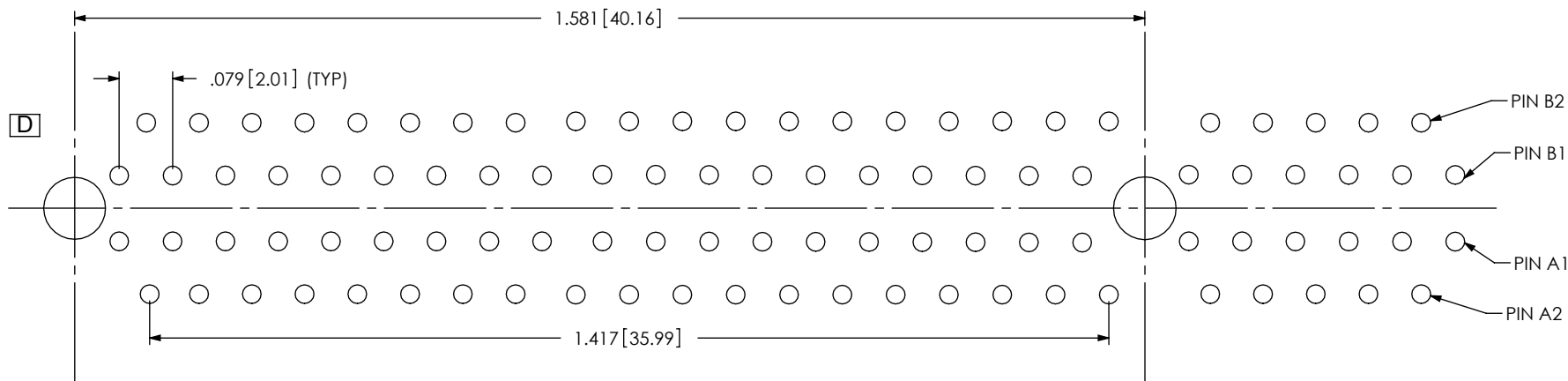


FIG 2
RECOMMENDED PCB LAYOUT
(FOR: -098)
(SAME AS FIG 1 UNLESS OTHERWISE NOTED)

No OF POS	TABLE 1	
	"C"	"D"
-036	0.236 [6.00]	0.360 [9.15]
-064	0.787 [20.00]	0.911 [23.15]
-164	2.756 [70.00]	2.880 [73.15]

NOTES:

1. ALL DIMENSIONS ARE SYMMETRIC ABOUT THE CENTERLINE.

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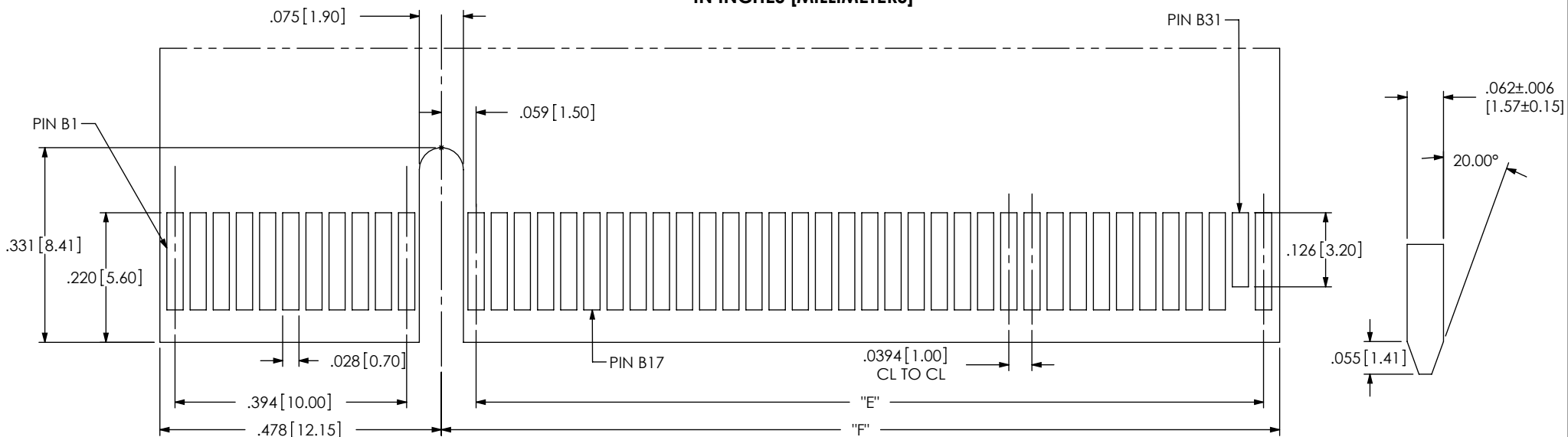


FIG 3
MATING CARD
PRIMARY (COMPONENT) SIDE

TABLE 2

No OF POS	"E"	"F"
-036	0.236 [6.00]	0.321 [8.15]
-064	0.787 [20.00]	0.872 [22.15]
-098	1.458 [37.03]	1.542 [39.17]
-164	2.756 [70.00]	2.841 [72.15]

D

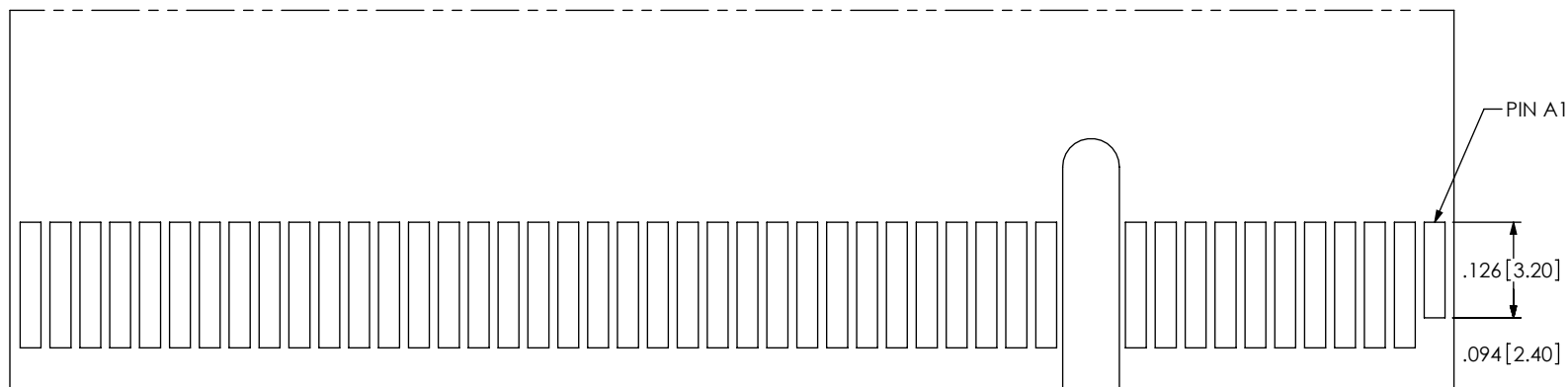


FIG 4
MATING CARD
SECONDARY (SOLDER) SIDE

NOTES:

1. PLATING TO BE .000030 INCHES GOLD WITH A HARDNESS OF 130-200 KNOOP PER ASTM B 488 TYPE 2, GRACE C.
2. ALL DIMENSIONS ARE SYMMETRIC ABOUT THE CENTERLINE.
3. PCIE SPECIFICATION TO SUPERSEDE SAMTEC RECOMMENDED LAYOUT.

F:\DWG\MISC\Mktg\Footprint\PCIE-XXX-02-X-D-TH-FOOTPRINT.SLDRW

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